

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT2997512

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHUN-LIANG SHEN	06/27/2014
MING-YUAN WU	06/27/2014
CHIUNG-HAN YEY	07/04/2014
KONG-BENG THEI	07/07/2014
HARRY-HAK-LAY CHUANG	07/07/2014
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14090757
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	214-651-5000
Email:	ipdocketing@haynesboone.com
Correspondent Name:	HAYNES AND BOONE, LLP
Address Line 1:	2323 VICTORY AVENUE
Address Line 2:	SUITE 700
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	2008-0490-D / 24061.2669
NAME OF SUBMITTER:	DAVID M. O'DELL
SIGNATURE:	/David M. O'Dell/
DATE SIGNED:	08/26/2014
Total Attachments: 6	

PATENT

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Docket No.: 2008-0490-D/24061.2669

Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|----------------------|----|--|
| (1) | Chun-Liang Shen | of | 1F., No. 149, Baoping Rd., Yonghe Dist.
New Taipei City 234 TW |
| (2) | Ming-Yuan Wu | of | 9F., No. 49, Jianzhong Rd., East Dist.
Hsinchu City 300 TW |
| (3) | Chiung-Han Yeh | of | No. 214, Dawu St., North Dist.
Tainan City 704 TW |
| (4) | Kong-Beng Thei | of | No. 56, Nan-Kang 3 rd Road,
Pao-Shan Village, Hsin-Chu Country, TW |
| (5) | Harry-Hak-Lay Chuang | of | 51 Paya Lebar
Crescent, Singapore 536191 |

have invented certain improvements in

PHOTO ALIGNMENT MARK FOR GATE LAST PROCESS

for which we have executed an application for Letters Patent of the United States of America, filed on November 26, 2013 and assigned application number 14/090,757; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on

Docket No.: 2008-0490-D/24061.2669
Customer No.: 000042717

applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: **Chun-Liang Shen**

Residence Address: 1F., No. 149, Baoping Rd., Yonghe Dist.
New Taipei City 234 TW

Dated: 2014.6.27

Chun-Liang Shen
Inventor Signature

Inventor Name: **Ming-Yuan Wu**

Residence Address: 9F., No. 49, Jianzhong Rd., East Dist.
Hsinchu City 300 TW

Dated: 2014.7.7

Ming-Yuan Wu
Inventor Signature

Inventor Name: **Chiung-Han Yeh**

Residence Address: No. 214, Dawu St., North Dist.
Tainan City 704 TW

Dated: _____

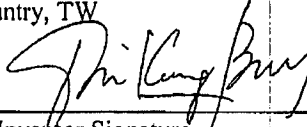
Inventor Signature

Docket No.: 2008-0490-D/24061.2669
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Inventor Name: **Kong-Beng Thei**

Residence Address: No. 56, Nan-Kang 3rd Road,
Pao-Shan Village, Hsin-Chu Country, TW

Dated: 2014-7-7


Inventor Signature

Inventor Name: **Harry-Hak-Lay Chuang**

Residence Address: 51 Paya Lebar
Crescent, Singapore 536191

Dated: 2014-7-7


Inventor Signature

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NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on

country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Residence Address: 1F., No. 149, Baoping Rd., Yonghe Dist.
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Dated: _____

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Hsinchu City 300 TW

Dated: _____

Inventor Signature

Inventor Name: **Chiung-Han Yeh**

Residence Address: No. 214, Dawu St., North Dist.
Tainan City 704 TW

Dated: 7.4.2014

Chiung Han Yeh
Inventor Signature

Inventor Name: **Kong-Beng Thei**

Residence Address: No. 56, Nan-Kang 3rd Road,
Pao-Shan Village, Hsin-Chu Country, TW

Dated: _____

Inventor Signature

Inventor Name: **Harry-Hak-Lay Chuang**

Residence Address: 51 Paya Lebar
Crescent, Singapore 536191

Dated: _____

Inventor Signature
